RELIABILITY REPORT

FOR

MAX4940CTN+

PLASTIC ENCAPSULATED DEVICES

September 29, 2009

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
Director, Reliability Engineering

Conclusion

The MAX4940CTN+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim's quality and reliability standards.

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I. Device Description

A. General

The MAX4940/MAX4940A integrated circuits generate high-voltage, high-frequency, unipolar or bipolar pulses from low-voltage logic inputs. These quad/dual pulsers feature independent logic inputs, independent high-voltage pulser outputs with active clamps and independent high-voltage supply inputs. The MAX4940/MAX4940A feature quad, high-voltage pulsers with 8.5 output impedance for the high-voltage outputs and a 21 impedance for the active clamp. The high-voltage outputs can provide 2.0A (typ) output current. All devices use two logic inputs per channel to control the positive and negative pulses. The MAX4940/MAX4940A have a dedicated input to control the active clamp. All devices feature an independent enable input EN. All digital inputs are CMOS compatible (see the Ordering Information/Selector Guide in the full data sheet). The MAX4940/MAX4940A are available in a 56-pin, 8mm x 8mm, TQFN exposed pad package and are specified over the 0NC to +70NC commercial temperature range. **Warning**: *Exercise caution. The MAX4940/MAX4940A are designed to operate with high voltages.*

II. Manufacturing Information

A. Description/Function:	Dual/Quad, Unipolar/Bipolar, High-Voltage Digital Pulsers
B. Process:	BCD250
C. Number of Device Transistors:	1828
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	9/4/09

III. Packaging Information

A. Package Type:	56-pin TQFN 8x8
B. Lead Frame:	Copper
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-3602
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 3
J. Single Layer Theta Ja:	35°C/W
K. Single Layer Theta Jc:	0.6°C/W
L. Multi Layer Theta Ja:	21°C/W
M. Multi Layer Theta Jc:	0.6°C/W

IV. Die Information

A. Dimensions:	244 X 197 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	Metal1 = 1.5µm / Metal2 = 3.0µm
F. Minimum Metal Spacing:	Metal1 = 1.5µm / Metal2 = 3.0µm
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 46 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 23.3 \times 10^{-9}$

λ = 23.3 F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at http://www.maxim-ic.com/qa/reliability/monitor. Cumulative monitor data for the BCD250 Process results in a FIT Rate of 0.43 @ 25C and 7.42 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The AJ75 die type has been found to have all pins able to withstand a HBM transient pulse of +/-2500 V per JEDEC JESD22-A114. Latch-Up testing has shown that this device withstands a current of +/-250 mA, 1.5x VCCMax overvoltage per JEDEC JESD78.

Table 1

Reliability Evaluation Test Results

MAX4940CTN+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	46	0
Moisture Testing (Note 2)				
HAST	Ta = 130°C RH = 85% Biased Time = 96hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.

Note 2: Generic Package/Process data